

CURRICULUM VITAE

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Tamil nadu.

Objective:

To associate with a progressive organization that gives scope to involve my knowledge and skills in the area of development and designing in electronics with the best of my capabilities while working in an innovative and dedicated team.

Total years of Experience:

Overall experience around 2 years 5 month in PCB designing.

Job description:

Designing of single, double and multilayered PCB boards having analog, mixed signal and high speed electronic circuits.

- Schematic design, Error checking and net list extraction
- PCB Parts Library Creation
- Major & Discrete components Placement as per customer needs
- Basic Transmission line concepts to pursue PCB design
- Framing and Implementing Testability (DFT) and Manufacturability(DFM) guidelines
- Stack up verification
- Signal grouping and classification
- Constraints settings
- Plane splitting & Power dropping
- Routing - Clock Signals, Critical signals, Differential pair, Bus & Single Ended Traces with noise consideration.
- DRC checking and clearing
- Gerber files generation and viewing

Highlights:

- Experience in Multilayer High Speed Printed Circuit Board Layout Design.
- Expertise in High Speed Routing, Length Matching like, DDR, SDRAM, PCI, PCIX and Constraint setting.
- Expertise in Part Decal creation, Schematic symbol creation and drawing schematic diagram.

ACADAMIC PROFILE:

- BSC in Electronics (2007 -2010)
- C.Abdul Hakeem college,
- Melvishram,
- Vellore - 632509

Skill Set:

EDA (Engineering Design Automation) Tools:

- PCB Design Tool : Cadence – Allegro 16.2,16.3 & 16.5
- Schematic Design tools : Cadence – Orcad version 16.2, 16.3 &16.5.
- Operating Systems : Windows 98,2000, XP,2007
- Interface : USB, Ethernet, DDR, SDRAM, PCI.
- Application Packages : Ms-office

Projects:

1. SODIMM-MDDR:

Description:

This project comprises a series of dynamic random access memory integrated circuits. These modules are mounted on a printed circuit board and designed for use in personal computers, workstations and servers.

Features:

- 6 Layers stack up with 63mils thickness.
- Maximum number of pins in single IC is 654.
- The minimum pitch across pins is 31.5 mils with 4mils trace width & 3.7mils spacing.
- The minimum drill size used in the board is 10 mils.

Components:

- PCI Edge connector.
- SODIUM SDRAM

2. VEHICLE TRACKING BOARD :

Description:

The Vehicle tracking board delivers high speed network connectivity to vehicles by leveraging the 3G network. It provides a seamless connection regardless how fast you are traveling. This allows users in and around the vehicle to access the Internet using any Wi-Fi enabled device.

Features:

- 10 Layers stack up with 63mils thickness.
- Maximum number of pins in single IC is 2518.
- The minimum pitch across pins is 19.6mils with 4 mils trace width & 4mils spacing.
- The minimum drill size used in the board is 9 mils.

Components:

- GSM Module with Built in GPS
- MCU 16BIT 128K FLASH 80-QFP
- MCU ARM11 400MHZ
- DDR2 SDRAM 512MBIT

3. DIGITAL FFT SPECTROMETER : (A/D CONVERTER)

Description:

This project used to convert the high frequency input analog signal to digital LVDS signal. The analog data input signal from SMA connector is given to A/D convertor. The encoded data is demultiplexed into 16 low-power LVDS signals. Then the 16 LVDS signal is given to two DMUX unit. This unit delivers the 16 LVDS signal to FMC connector from 8 LVDS input.

Features:

- 10 Layers stack up with 63mils thickness.
- Maximum number of pins in single IC is 243.
- The minimum pitch across pins is 19.69 mils with 4mils trace width & 4 mils spacing.
- The minimum drill size used in the board is 12 mils.

Components:

- ASNT7120KMA 10.0 GSPS A/D converter (100 PIN CQFP package)
- ASTN2032MBL DMUX with LVDS interface (BGA 243)
- ASTN134488-01 FMC connector male with 400 pin pos
- SMA connector

3. BIB (Burn in Board):

Description:

I have designed a process (BIB) done to components prior to regular use in which the components are stressed to detect failure and ensure component reliability.

Features:

- This board has 12 Layers stack up with the board size of 22.67”x 11.04” with 63 mils thickness.
- Used 40 Socket of BGA with the pin count of 225.
- The design consist of blind & buried via (6/12) for bga fanout.
- The design consist constrains 5mil trace width and 5 mil spacing, via used 15/30.

4. Non-High-Speed Boards:

Description:

I have designed various types of transmitter, receiver, sensor and adapter boards using 2 to 6 layers.

Transmitter board Features:

- 2 /6Layers stack up with 63mils thickness.
- The minimum pitch across pins is 25.5 mils with 5mils trace width & 5mils spacing.
- The minimum drill size used in the board is 10 mils.

5. ATE Boards:

Description:

Automated Test Equipments PCB used to by silicon vendors to check their ic’s for production.

Features:

- 32 Layers stack up with 293mils thickness.
- Maximum number of pins in BGA is 2808.
- The minimum pitch across pins is 39.37 mils with 5.5mils trace width & 4.9mils spacing.
- The minimum drill size used in the board is 14 mils.

EXPERIENCE:

- Working as a Layout Designer in Virya InfoTech, Chennai, since June '2011 to till date.

Personal Information:

Name : XXXXX
Father's Name : Mr. C.Ravi
Age & Date of Birth : 25 years, 13th October 1988.
Languages known : Tamil, English.
Nationality : Indian
Permanent address : XXXXXX

I hereby declare that information furnished above is true to best of my knowledge and belief.

PLACE: Chennai

yours faithfully,

DATE:

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